

Super Solution Power Module (SUSPM™)

2pack IGBT Module

Features

- Trench Field Stop Technology IGBT
 - low saturation voltage
 - positive temperature coefficient
 - fast switching($\leq 20\text{kHz}$)
 - high ruggedness(UIS tested)
- Free wheeling diodes with fast and soft reverse recovery
- Industrial standard package with insulated copper base plate
- 10us @ $T_J=125\text{K}$ Short circuit rated
- Included gate surge protection function



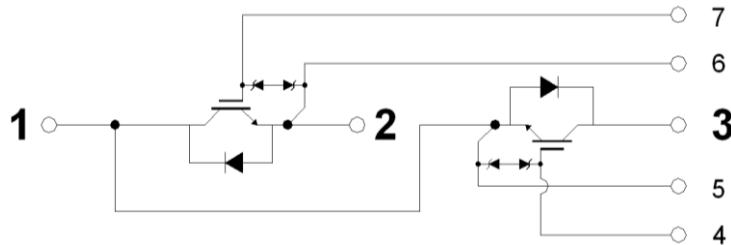
SUSPM™ 2

1200V / 200A

Applications

- Welder
- Switched Mode Power Supply / UPS
- Industrial Inverter

Internal Equivalent Circuit



Absolute Maximum Ratings

Item	Symbol	conditions	Ratings	Unit
IGBT	V_{CES}		1200	V
	V_{GES}	continuous	± 20	V
	V_{GEM}	transient	± 28	V
	I_c	$T_c=80^\circ\text{C}$	200	A
	I_{CM}	$T_c = 80^\circ\text{C}$, $t_p=1\text{ms}$	400	A
	t_{sc}	$T_J=125^\circ\text{C}$, $V_{cc}=900\text{V}$; $V_{GE}=15\text{V}$;	10	us
	$T_{J,\text{MAX}}$		150	$^\circ\text{C}$
	P_D	$T_c=80^\circ\text{C}$	1000	W
Diode	V_{RRM}		1200	V
	$I_{F(AV)}$	$T_c=80^\circ\text{C}$	200	A
	I_{FRM}	$T_c=80^\circ\text{C}$; $t_p=1\text{ms}$	400	A
	$T_{J,\text{MAX}}$		150	$^\circ\text{C}$
	P_D	$T_c=80^\circ\text{C}$	500	W
Module	$T_{J,OP}$	Operation temperature	-40...+125	$^\circ\text{C}$
	T_{STG}	Storage temperature	-40...+125	$^\circ\text{C}$
	$Visol$	$I_{sol} \leq 1\text{mA}$; 50/60 Hz; AC 1min	2500	V
	M_t	Main Terminal Mounting torque (M6)	2.5 – 4.5	Nm
	M_s	Heat sink Mounting torque (M6)	3.0 – 5.0	Nm

Characteristic Values ($T_c=25^\circ\text{C}$, unless otherwise specified)

Item	Symbol	conditions	min	typ	max	Unit
IGBT	$V_{CE(\text{sat})}$	$T_c = 25^\circ\text{C}, I_c = 200\text{A}; V_{GE} = 15\text{V}$ $T_c = 125^\circ\text{C},$		1.7 2.0	2.2	V V
	$V_{GE(\text{th})}$	$I_c = 8.0\text{mA}; V_{GE} = V_{CE}; T_c = 25^\circ\text{C}$	5.0	5.8	6.5	V
	I_{CES}	$T_c = 25^\circ\text{C}, V_{CE} = 600\text{V}; V_{GE} = 0\text{V}$ $T_c = 125^\circ\text{C}$			2.0	mA
	I_{GES}	$V_{CE} = 0\text{V}; V_{GE} = \pm 20$	-400		400	nA
	$t_{(\text{on})}$	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$	Inductive load $V_{CC} = 600\text{V}; I_c = 200\text{A}$ $V_{GE} = \pm 15\text{V}; R_g = 3.6\text{ohm};$	250 300		ns
	t_r	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		90 100		ns
	$t_{d(\text{off})}$	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		550 650		ns
	t_f	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		130 180		ns
	E_{on}	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		15		mJ
	E_{off}	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		35		mJ
	C_{ies}	$V_{CC} = 25\text{V}; V_{GE} = 0\text{V}; f = 1\text{MHz}$		14		nF
	C_{res}	$V_{CC} = 25\text{V}; V_{GE} = 0\text{V}; f = 1\text{MHz}$		0.5		nF
	Q_G	$V_{CC} = 600\text{V}; V_{GE} = 15\text{V}; I_c = 200\text{A}$		0.95		uC
	R_{Gin}	$T_c = 25^\circ\text{C}$		3.8		ohm
	I_{sc}	$t_p \leq 10\text{us}, T_c = 125^\circ\text{C}, V_{CC} = 900\text{V}, V_{GE} = 15\text{V};$		800		A
	R_{thJC}	(per IGBT)		0.07		°C/W
Diode	V_F	$T_c = 25^\circ\text{C} ; I_F(AV) = 200\text{A}; V_{GE} = 0\text{V}$ $T_c = 125^\circ\text{C} ;$		1.7 1.7	2.2	V V
	I_{rr}	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$	Inductive load $V_R = 600\text{V} ; I_F = 150\text{A};$ $-dI_F/dt = 2000\text{A/us}$	150 190		A
	Q_{rr}	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		20 36		uC
	E_{rr}	$T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$		9 17		mJ
	R_{thJC}	(per diode)			0.14	°C/W
Module	ds	Creepage distance along surface		17		mm
	d_A	Clearance distance in the air		10.5		mm
	T_s	Pin terminal soldering temperature, 10sec		260		°C
	weight			240		gr

Package Dimensions (dimensions are millimeters, mm)